

**PROCESS FOR INHIBITING CORROSION AND REMOVING CONTAMINANT FROM
A SURFACE DURING WAFER DICING AND COMPOSITION USEFUL THEREOF**

ABSTRACT OF THE DISCLOSURE

5 Adherence of contaminant residues or particles is suppressed, corrosion of
exposed surfaces is substantially reduced or eliminated during the process of dicing a
wafer by sawing. A fluoride-free aqueous composition comprising a dicarboxylic acid
and/or salt thereof; a hydroxycarboxylic acid and/or salt thereof or amine group
10 containing acid, a surfactant and deionized water is employed.

Figure 8